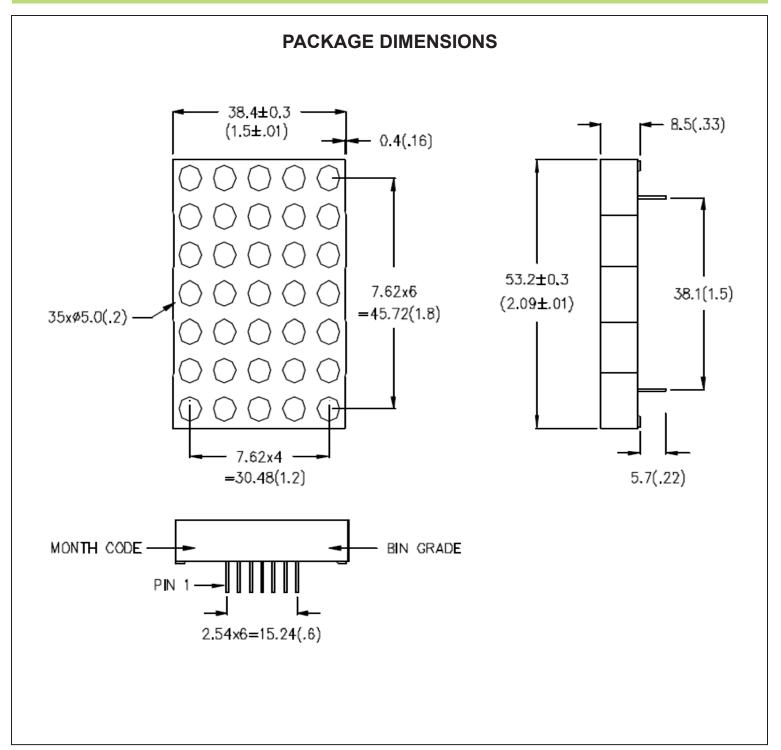


SPECIFICATIONS

CDMX5720 SERIES



Notes:

1. All dimensions are in millimeters (inches).

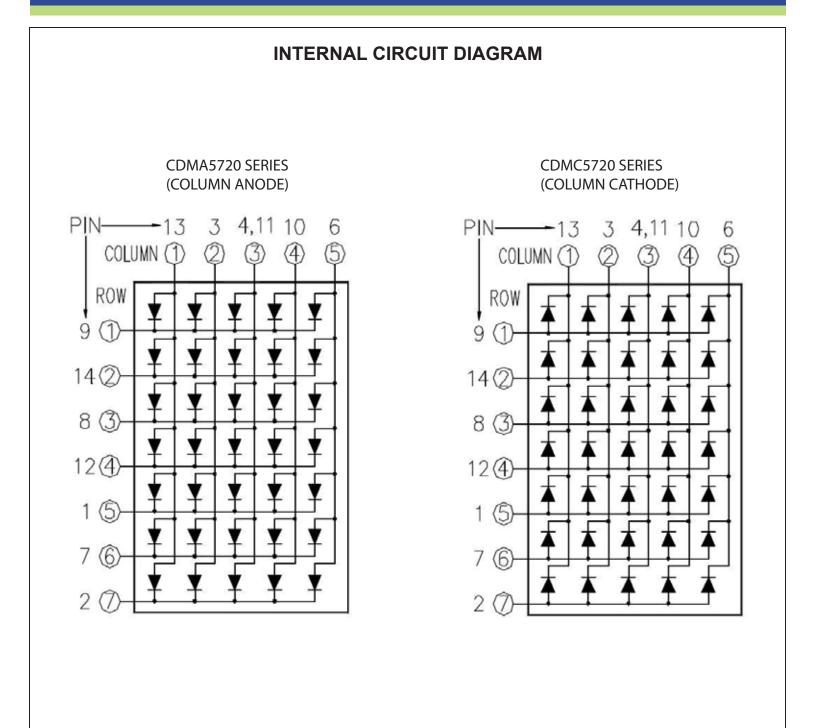
2. Tolerance is \pm 0.25mm (0.01") unless otherwised noted.

3. Specifications are subject to change without notice.





SPECIFICATIONS



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.

3. Specifications are subject to change without notice.





PART NUMBER DESCRIPTION

| Part Number | Chip Material | Color of Emission | Lens Type | Description |
|--------------|---------------|-------------------|---------------|----------------|
| CDMA5720R1W | GaAsP | Red | White Segment | Common Anode |
| CDMC5720R1W | GaAsP | Red | White Segment | Common Cathode |
| CDMA5720RR1W | AlGaAs | Super Red | White Segment | Common Anode |
| CDMC5720RR1W | AlGaAs | Super Red | White Segment | Common Cathode |
| CDMA5720Y1W | GaAsP | Yellow | White Segment | Common Anode |
| CDMC5720Y1W | GaAsP | Yellow | White Segment | Common Cathode |
| CDMA5720G1W | GaP | Green | White Segment | Common Anode |
| CDMC5720G1W | GaP | Green | White Segment | Common Cathode |

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

(TA=25°C

| | Wave- | Absolute Maximum | | | Electro-Optical Characteristics | | | | | | |
|--------------|----------------|------------------|----|-----|---------------------------------|--------|------|-----|------------------|-------|-------|
| Part Number | length (nm) | Δλ | PD | IAF | IPF | VF (V) | | lf | lv (µcd) | | |
| | (1111) | nm | mW | mA | (Peak) | Min | Тур | Max | (Rec) | Min | Тур |
| CDMA5720R1W | 625 | 45 | 75 | 30 | 100 | 1.7 | 1.85 | 2.5 | 10 | 6400 | 15000 |
| CDMC5720R1W | 625 | 45 | 75 | 30 | 100 | 1.7 | 1.85 | 2.5 | 10 | 6400 | 15000 |
| CDMA5720RR1W | 640 | 20 | 72 | 20 | 100 | 1.6 | 1.75 | 2.4 | 10 | 10500 | 30000 |
| CDMC5720RR1W | 640 | 20 | 72 | 20 | 100 | 1.6 | 1.75 | 2.4 | 10 | 10500 | 30000 |
| CDMA5720Y1W | 588 | 35 | 75 | 30 | 100 | 1.7 | 2.1 | 2.8 | 10 | 5000 | 9000 |
| CDMC5720Y1W | 588 | 35 | 75 | 30 | 100 | 1.7 | 2.1 | 2.8 | 10 | 5000 | 9000 |
| CDMA5720G1W | 568 | 30 | 65 | 30 | 100 | 1.7 | 2.1 | 2.8 | 10 | 8000 | 24000 |
| CDMC5720G1W | 568 | 30 | 65 | 30 | 100 | 1.7 | 2.1 | 2.8 | 10 | 8000 | 24000 |

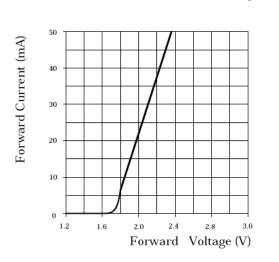
ABSOLUTE MAXIMUM RATINGS

| Reverse Voltage | 5V | Spectral Line half-width (λ) | nm |
|---------------------------|----------------------|---|----|
| Reverse Current (Vr = 5V) | 100µA | Power Dissipation (PD) | mW |
| Operating Temperature | -40°C~+85°C | Peak Forward Current (Duty 1/10, @ KHz) | mA |
| Storage Temperature | -40°C~+85°C | Recommended Operation Current (IF Rec) | mA |
| Soldering Temperature | 250C~260C for 3 sec. | Average Luminous Intensity (IF=10) | μA |

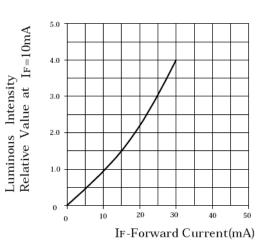




OPTICAL CHARACTERISTIC CURVES - RED

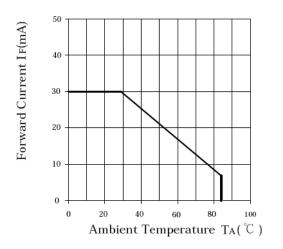


Forward Current vs. Forward Voltage

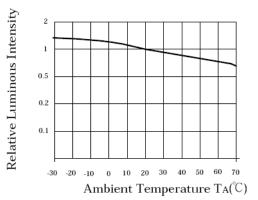


Relative Intensity vs. Forward Current

Forward Current vs. Ambient Temperature



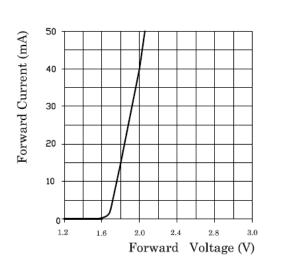
Luminous Intensity vs. Ambient Temperature



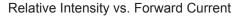


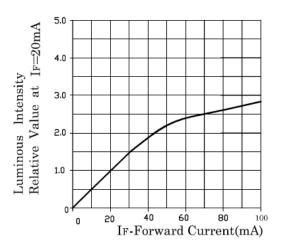


OPTICAL CHARACTERISTIC CURVES - SUPER RED

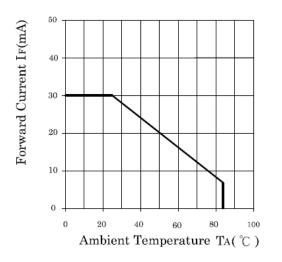


Forward Current vs. Forward Voltage

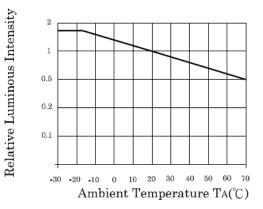




Forward Current vs. Ambient Temperature



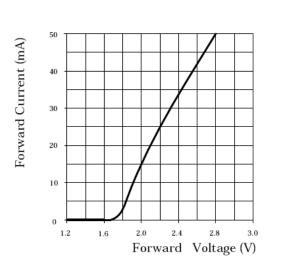
Luminous Intensity vs. Ambient Temperature



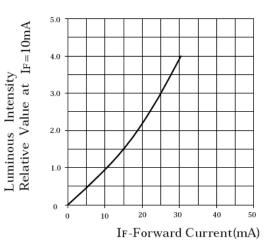




OPTICAL CHARACTERISTIC CURVES - YELLOW

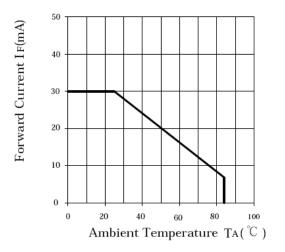


Forward Current vs. Forward Voltage

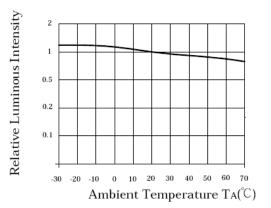


Relative Intensity vs. Forward Current

Forward Current vs. Ambient Temperature



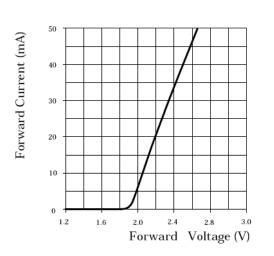
Luminous Intensity vs. Ambient Temperature



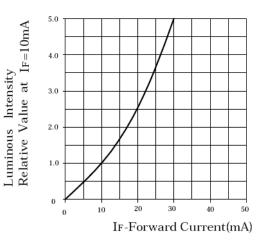




OPTICAL CHARACTERISTIC CURVES - GREEN

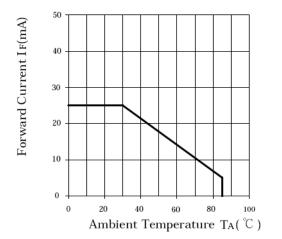


Forward Current vs. Forward Voltage



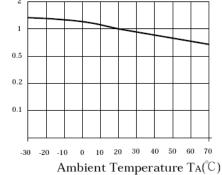
Relative Intensity vs. Forward Current

Luminous Intensity vs. Ambient Temperature



Forward Current vs. Ambient Temperature

Relative Luminous Intensity







SOLDERING CONDITIONS - DISPLAY

- * Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- * Recommended soldering conditions

| Dip Soldering | | | | |
|-------------------------|--|--|--|--|
| Pre-Heat | 100 °C Max | | | |
| Pre-Heat Time | 60 Second Max | | | |
| Solder Bath Temperature | 260 °C Max | | | |
| Dippng Time | 5 Second Max | | | |
| Dipping Position | No lower than 3mm from the base of the epoxy | | | |

| Hand Soldering | | | | |
|--|--|--|--|--|
| | 3mm Series | Others | | |
| Temperature Soldering Time Position | 300 °C Max 3 Second Max No closer than 3mm from the base of the epoxy | 350 °C Max 3 Second Max No closer than 3mm from the base of the epoxy | | |

- * Do not apply any stress to the lead. Particularly when heated.
- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.

